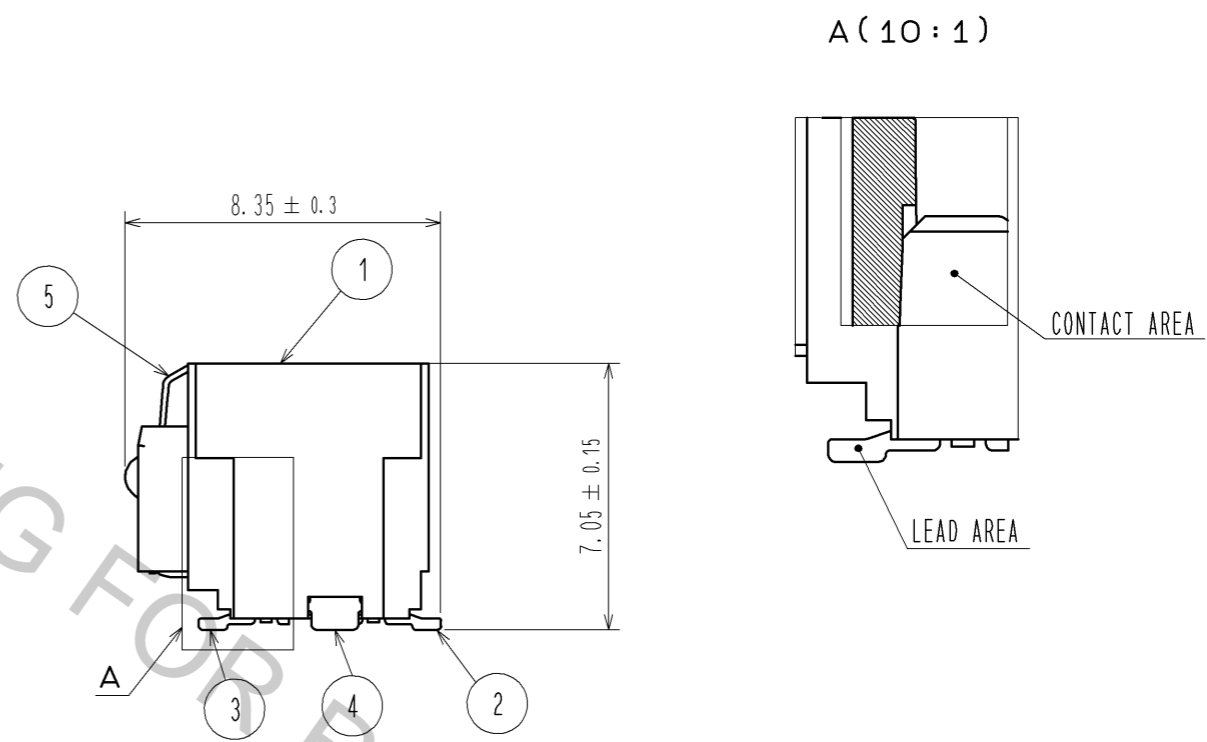
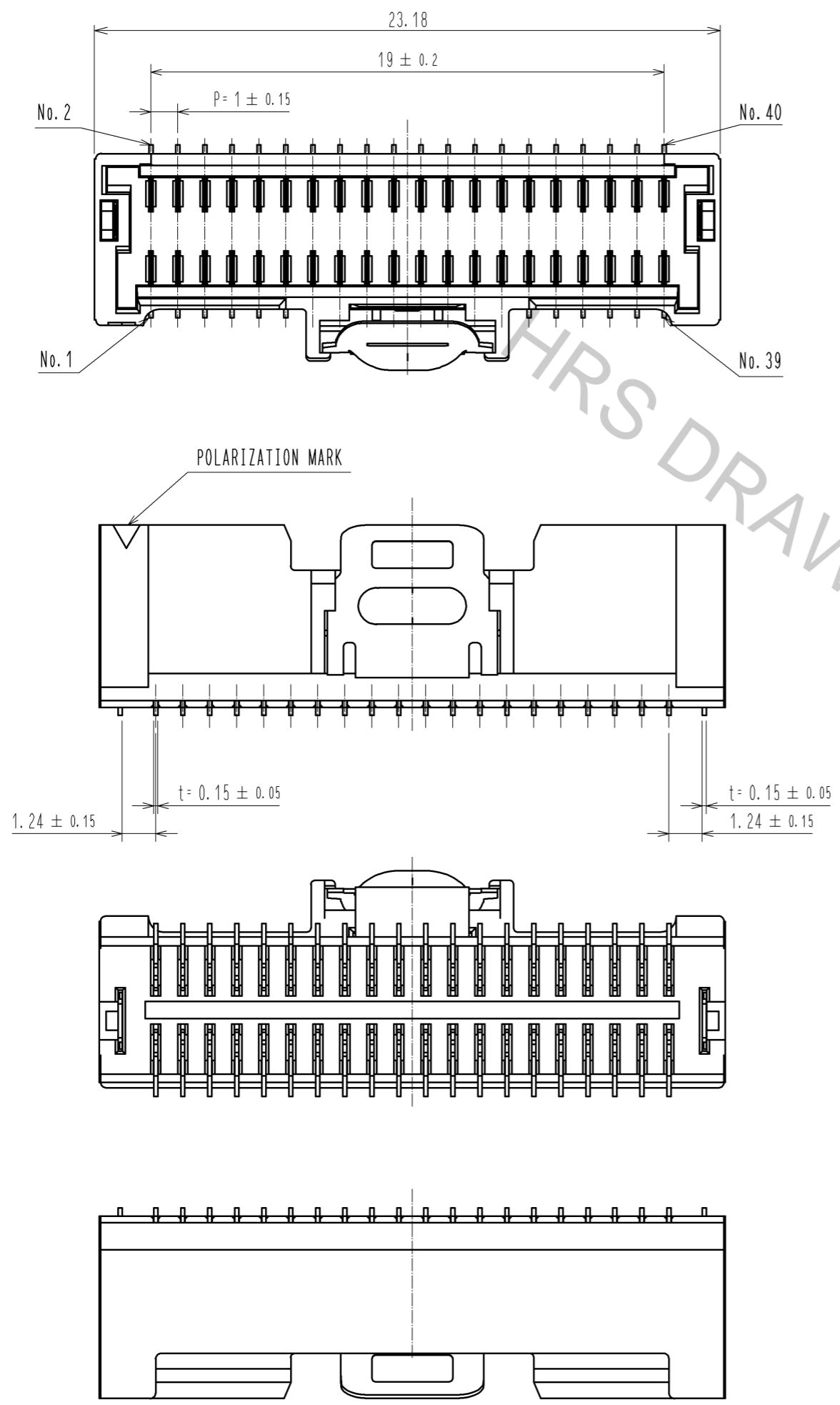


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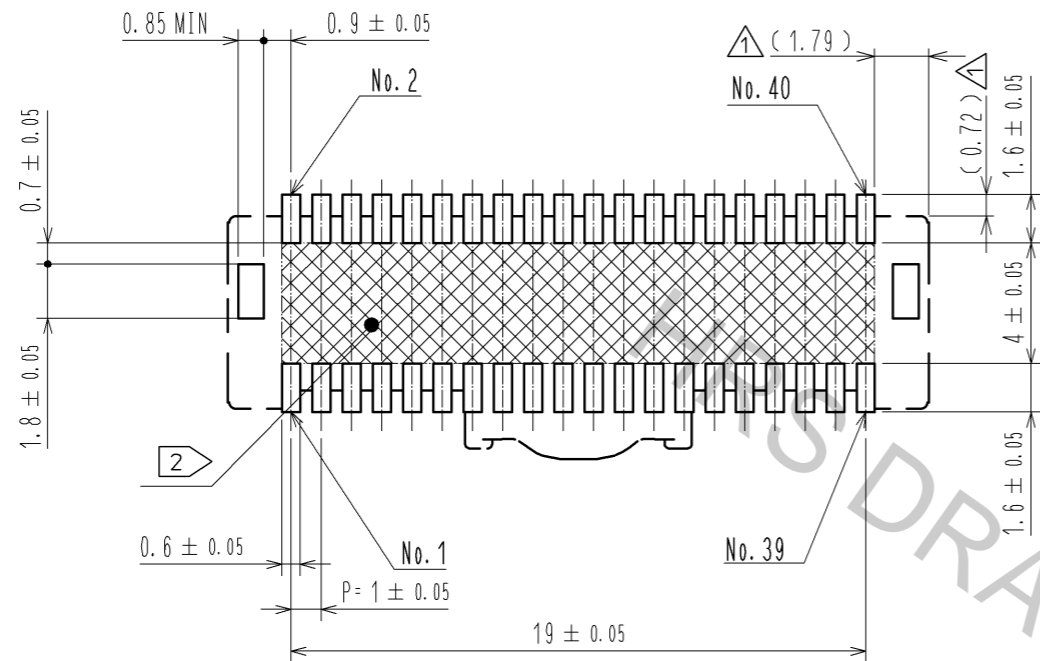


NOTES
 1. LEAD CO-PLANARITY SHALL BE 0.1 mm MAX.
 2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO EPC.

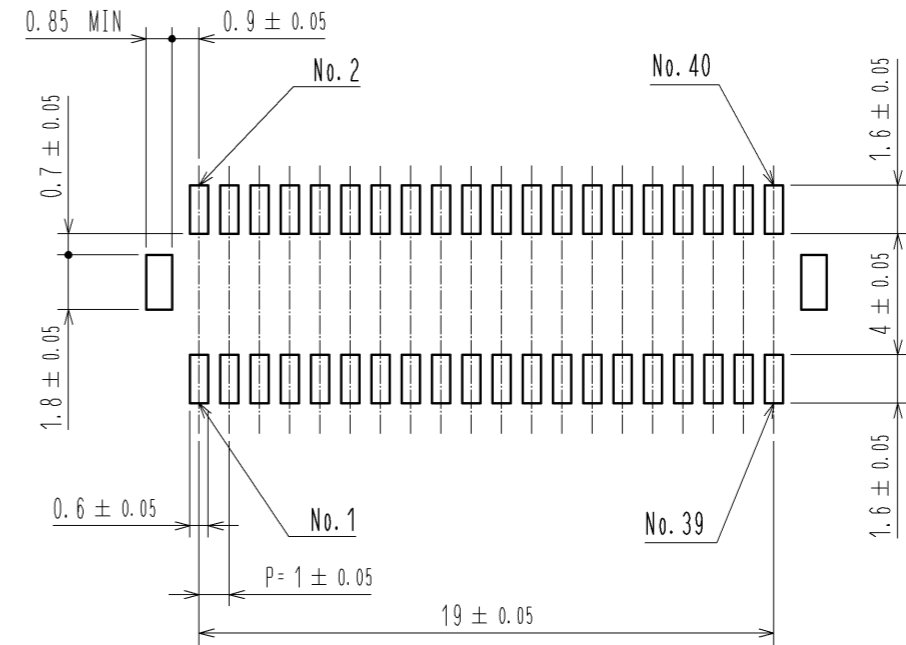
3	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN.	9	POLYAMIDE	VACUUM CAP
		LEAD AREA : Au PLATING 0.05μm MIN.	8	PS	REEL, BLACK
2	BRASS	UNDERPLATING : Ni PLATING 1μm MIN.	7	POLYESTER	CLEAR
		CONTACT AREA : Au PLATING 0.05μm MIN.	6	PS	CLEAR
1	LCP	LEAD AREA : Au PLATING 0.05μm MIN.	5	STAINLESS STEEL	-
		UNDERPLATING : Ni PLATING 1μm MIN.	4	BRASS	SURFACE : Sn PLATING 1μm MIN. UNDERPLATING : Ni PLATING 0.5μm MIN.
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE FREE	COUNT 4	DESCRIPTION OF REVISIONS DIS-H-007735	
APPROVED : KI. AKIYAMA		12.06.08		DESIGNED	MI. SAKIMURA
CHECKED : HK. UMEHARA		12.06.08		CHECKED	TS. KUMAZAWA
DESIGNED : TT. OHSAKO		10.05.14		DATE	13.03.22
DRAWN : TT. OHSAKO		10.05.14		DRAWING NO. EDC3-324909-03	
				PART NO. DF50-40DP-1V(52)	
				CODE NO. CL665-0005-9-52	

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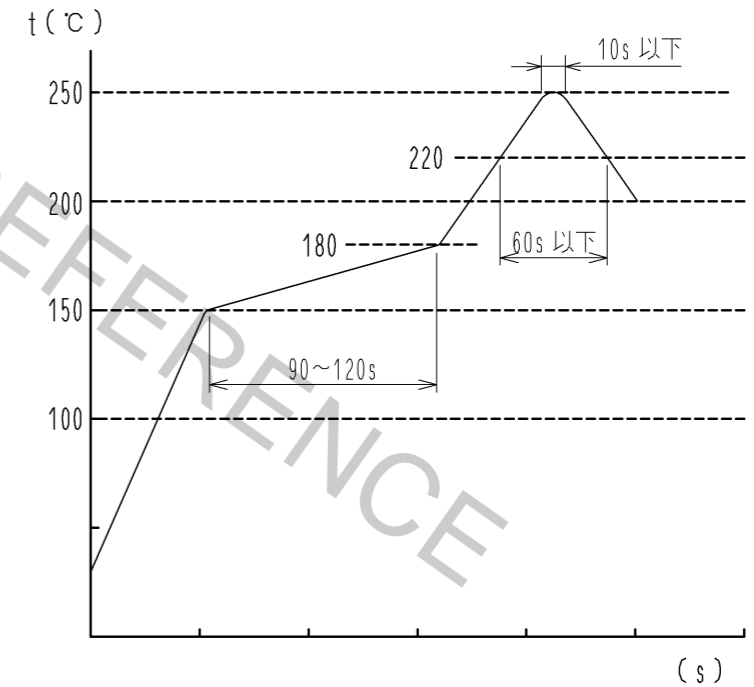
RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)



RECOMMENDED METAL MASK (FREE)
THICKNESS : 0.1mm



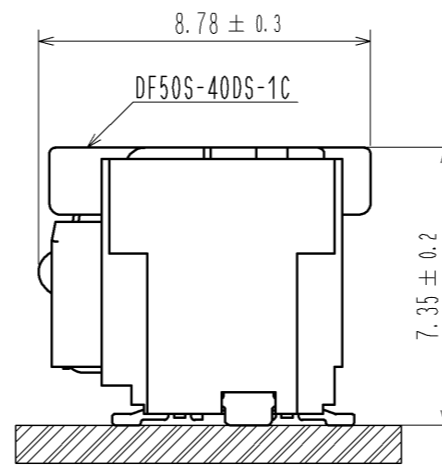
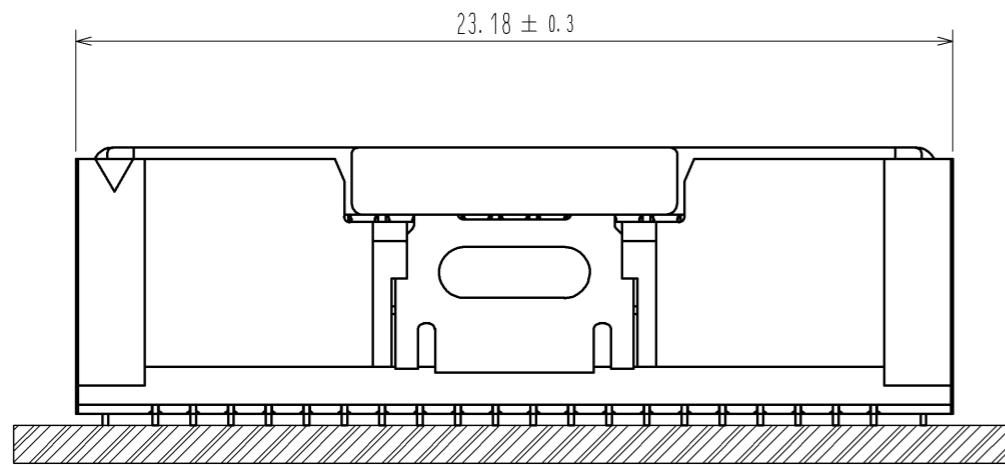
REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE(REFERENCE)



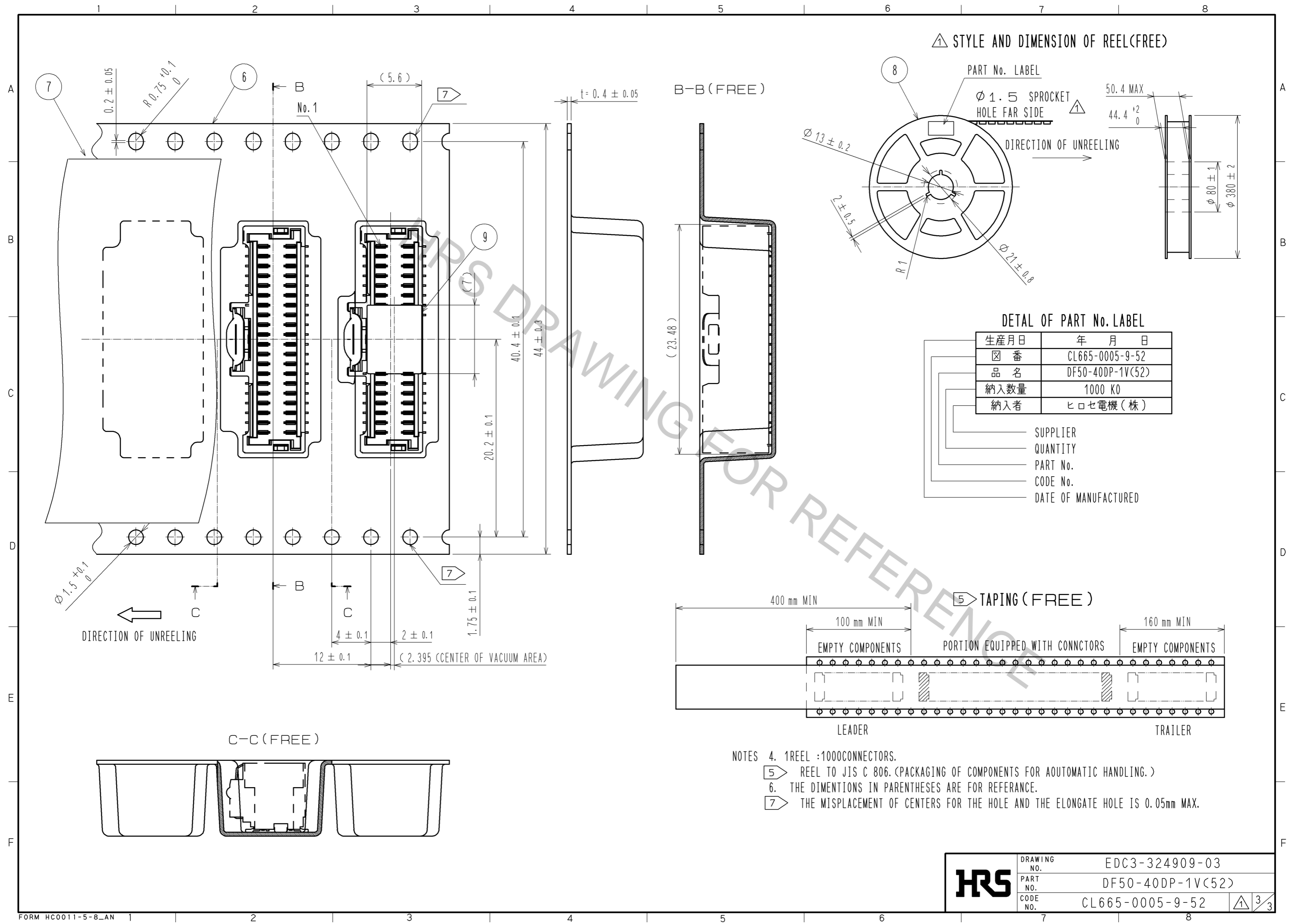
NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING
CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED
BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING
METAL etc.

MATING FIGURE (5 : 1)



HRS	DRAWING NO.	EDC3-324909-03
	PART NO.	DF50-40DP-1V(52)
	CODE NO.	CL665-0005-9-52
		2/3



HRS	DRAWING NO.	EDC3-324909-03
	PART NO.	DF50-40DP-1V(52)
	CODE NO.	CL665-0005-9-52
		△ 3/3